

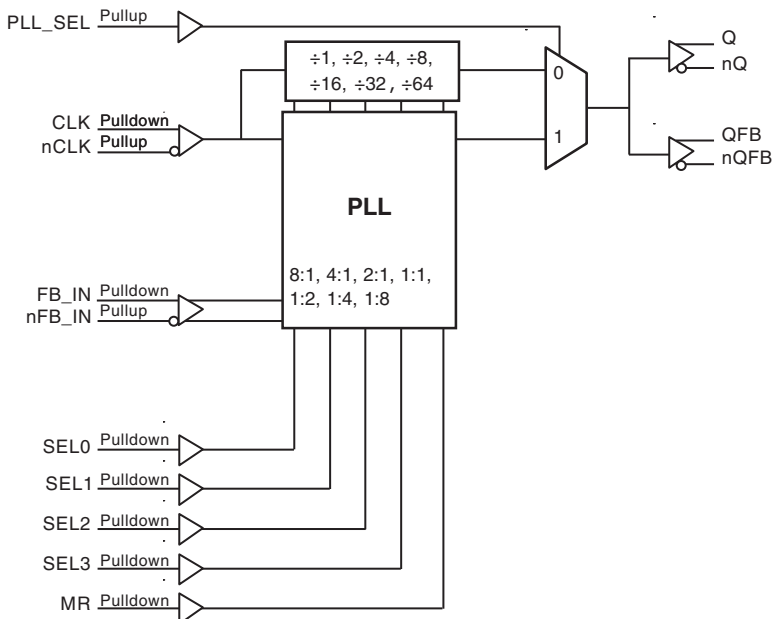
General Description

The 8745B-21 is a highly versatile 1:1 LVDS Clock Generator. The 8745B-21 has a fully integrated PLL and can be configured as zero delay buffer, multiplier or divider, and has an output frequency range of 31.25MHz to 700MHz. The Reference Divider, Feedback Divider and Output Divider are each programmable, thereby allowing for the following output-to-input frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8. The external feedback allows the device to achieve “zero delay” between the input clock and the output clock. The PLL_SEL pin can be used to bypass the PLL for system test and debug purposes. In bypass mode, the reference clock is routed around the PLL and into the internal output dividers.

Features

- One differential LVDS output designed to meet or exceed the requirements of ANSI TIA/EIA-644 One differential feedback output pair
- Differential CLK, nCLK input pair
- CLKx, nCLKx pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- Output frequency range: 31.25MHz to 700MHz
- Input frequency range: 31.25MHz to 700MHz
- VCO range: 250MHz to 700MHz
- External feedback for “zero delay” clock regeneration with configurable frequencies
- Programmable dividers allow for the following output-to-input frequency ratios: 8:1, 4:1, 2:1, 1:1, 1:2, 1:4, 1:8
- Cycle-to-cycle jitter: 30ps (maximum)
- Output skew: 35ps (maximum)
- Static phase offset: 25ps ± 125ps
- Full 3.3V supply voltage
- 0°C to 70°C ambient operating temperature
- Available in lead-free (RoHS 6) package

Block Diagram



Pin Assignment

CLK	1	20	SEL1
nCLK	2	19	SEL0
MR	3	18	V _{DD}
nFB_IN	4	17	PLL_SEL
FB_IN	5	16	V _{DDA}
SEL2	6	15	SEL3
V _{DDO}	7	14	GND
nQFB	8	13	Q
QFB	9	12	nQ
GND	10	11	V _{DDO}

8745B-21

20-Lead SOIC

7.5mm x 12.8mm x 2.3mm package body

M Package

Top View

Table 1. Pin Descriptions

Number	Name	Type		Description
1	CLK	Input	Pulldown	Non-inverting differential clock input.
2	nCLK	Input	Pullup	Inverting differential clock input.
3	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true output Q to go low and the inverted output nQ to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTTL interface levels.
4	nFBIN	Input	Pullup	Inverting differential feedback input to phase detector for regenerating clocks with "Zero Delay."
5	FBIN	Input	Pulldown	Non-inverted differential feedback input to phase detector for regenerating clocks with "Zero Delay."
6, 15, 19, 20	SEL2, SEL3, SEL0 SEL1	Input	Pulldown	Determines output divider values in Table 3. LVCMOS / LVTTTL interface levels.
7, 11	V _{DDO}	Power		Output supply pins.
8, 9	nQFB/QFB	Output		Differential feedback output pair. LVDS interface levels.
10, 14	GND	Power		Power supply ground.
12, 13	nQ/Q	Output		Differential output pair. LVDS interface levels.
16	V _{DDA}	Power		Analog supply pin.
17	PLL_SEL	Input	Pullup	PLL select. Selects between the PLL and reference clock as the input to the dividers. When LOW, selects reference clock. LVCMOS/LVTTTL interface levels.
18	V _{DD}	Power		Core supply pin.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		kΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ

Function Tables

Table 3A. Control Input Function Table

Inputs					Outputs PLL_SEL = 1 PLL Enable Mode
SEL3	SEL2	SEL1	SEL0	Reference Frequency Range (MHz)*	Q, nQ
0	0	0	0	250 - 700	÷1
0	0	0	1	125 - 350	÷1
0	0	1	0	62.5 - 175	÷1
0	0	1	1	31.25 - 87.5	÷1
0	1	0	0	250 - 700	÷2
0	1	0	1	125 - 350	÷2
0	1	1	0	62.5 - 175	÷2
0	1	1	1	250 - 700	÷4
1	0	0	0	125 - 350	÷4
1	0	0	1	250 - 700	÷8
1	0	1	0	125 - 350	x2
1	0	1	1	62.5 - 175	x2
1	1	0	0	31.25 - 87.5	x2
1	1	0	1	62.5 - 175	x4
1	1	1	0	31.25 - 87.5	x4
1	1	1	1	31.25 - 87.5	x8

*NOTE: VCO frequency range for all configurations above is 250MHz to 700MHz.

Table 3B. PLL Bypass Function Table

Inputs				Outputs PLL_SEL = 0 PLL Bypass Mode
SEL3	SEL2	SEL1	SEL0	Q, nQ
0	0	0	0	÷4
0	0	0	1	÷4
0	0	1	0	÷4
0	0	1	1	÷8
0	1	0	0	÷8
0	1	0	1	÷8
0	1	1	0	÷16
0	1	1	1	÷16
1	0	0	0	÷32
1	0	0	1	÷64
1	0	1	0	÷2
1	0	1	1	÷2
1	1	0	0	÷4
1	1	0	1	÷1
1	1	1	0	÷2
1	1	1	1	÷1

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to $V_{DD} + 0.5V$
Outputs, I_O Continuous Current Surge Current	10mA 15mA
Package Thermal Impedance, θ_{JA}	46.2°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. LVDS Power Supply DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDA}	Analog Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		3.135	3.3	3.465	V
I_{DD}	Power Supply Current				125	mA
I_{DDA}	Analog Supply Current				17	mA
I_{DDO}	Output Supply Current				59	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage		-0.3		0.8	V
I_{IH}	Input High Current	SEL[0:3], MR	$V_{DD} = V_{IN} = 3.465V$		150	μA
		PLL_SEL	$V_{DD} = V_{IN} = 3.465V$		5	μA
I_{IL}	Input Low Current	SEL[0:3], MR	$V_{DD} = 3.465V, V_{IN} = 0V$	-5		μA
		PLL_SEL	$V_{DD} = 3.465V, V_{IN} = 0V$	-150		μA

Table 4C. Differential DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK, FB_IN	$V_{DD} = V_{IN} = 3.465V$			150	μA
		nCLK, nFB_IN	$V_{DD} = V_{IN} = 3.465V$			5	μA
I_{IL}	Input Low Current	CLK, FB_IN	$V_{DD} = 3.465V,$ $V_{IN} = 0V$	-5			μA
		nCLK, nFB_IN	$V_{DD} = 3.465V,$ $V_{IN} = 0V$	-150			μA
V_{PP}	Peak-to-Peak Voltage; NOTE 1			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2			GND + 0.5		$V_{DD} - 0.85$	V

NOTE 1: V_{IL} should not be less than -0.3V.

NOTE 2: Common mode input voltage is defined as V_{IH} .

Table 4D. LVDS DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OD}	Differential Output Voltage		320	440	550	mV
ΔV_{OD}	V_{OD} Magnitude Change			0	50	mV
V_{OS}	Offset Voltage		1.05	1.2	1.35	V
ΔV_{OS}	V_{OS} Magnitude Change				25	mV

Table 5. Input Frequency Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ to $70^\circ C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
F_{IN}	Input Frequency	CLK, nCLK	PLL_SEL = 1	31.25		700	μA
			PLL_SEL = 0			700	V

AC Electrical Characteristics

Table 6. AC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$, $T_A = 0^\circ\text{C}$ to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				700	MHz
t_{PD}	Propagation Delay; NOTE 1	PLL_SEL = 0V, $f \leq 700\text{MHz}$	3.1	3.4	4.0	ns
$t_{sk}(\emptyset)$	Static Phase Offset; NOTE 2, 5	PLL_SEL = 3.3V	-100	25	150	ps
$t_{sk}(o)$	Output Skew; NOTE 3, 5				35	ps
$f_{jit}(cc)$	Cycle-to-Cycle Jitter; NOTE 5, 6				30	ps
$f_{jit}(\theta)$	Phase Jitter; NOTE 4, 5, 6				± 52	ps
t_L	PLL Lock Time				1	ms
t_R / t_F	Output Rise/Fall Time; NOTE 7	20% to 80%	200		700	ps
odc	Output Duty Cycle		46	50	54	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as the time difference between the input reference clock and the averaged feedback input signal across all conditions, when the PLL is locked and the input reference frequency is stable.

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

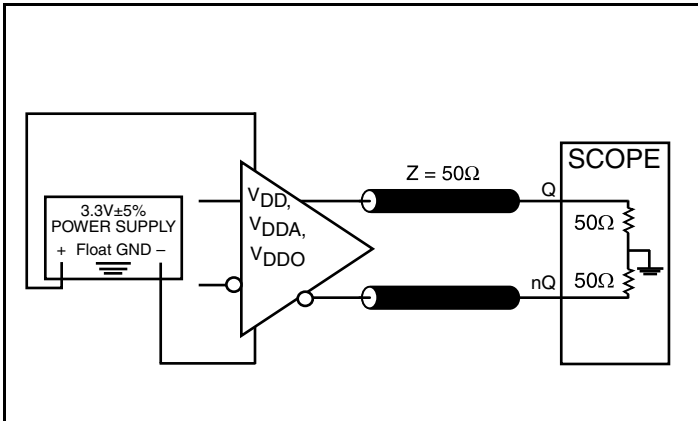
NOTE 4: Phase jitter is dependent on the input source used.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

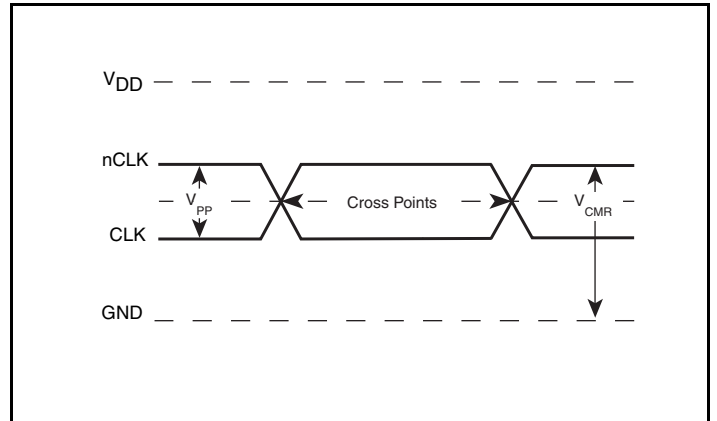
NOTE 6: Characterized at VCO frequency of 622MHz.

NOTE 7: Measured from the 20% to 80% points. Guaranteed by characterization. Not production tested.

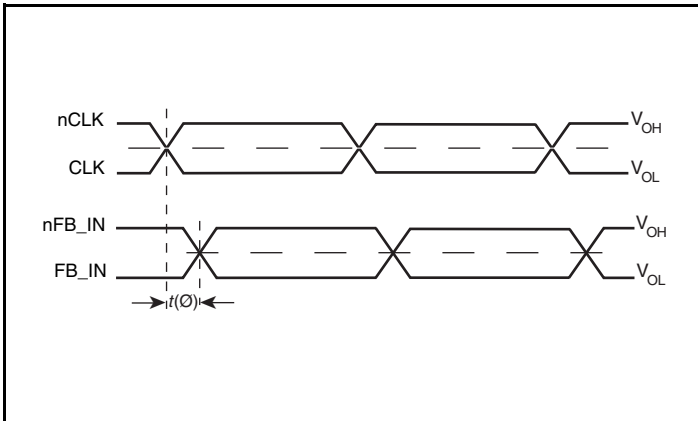
Parameter Measurement Information



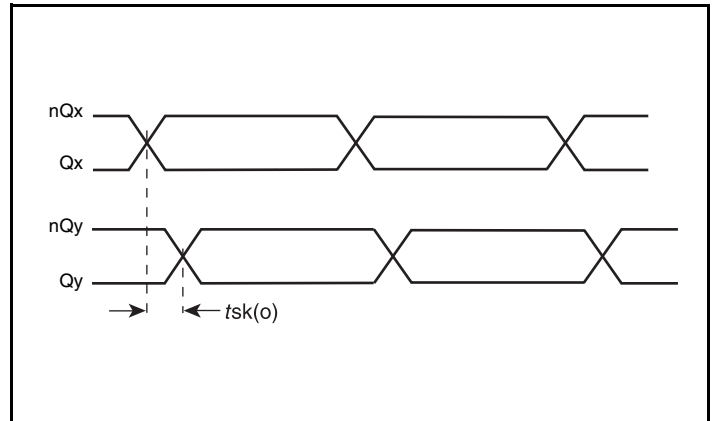
3.3V LVDS Output Load AC Test Circuit



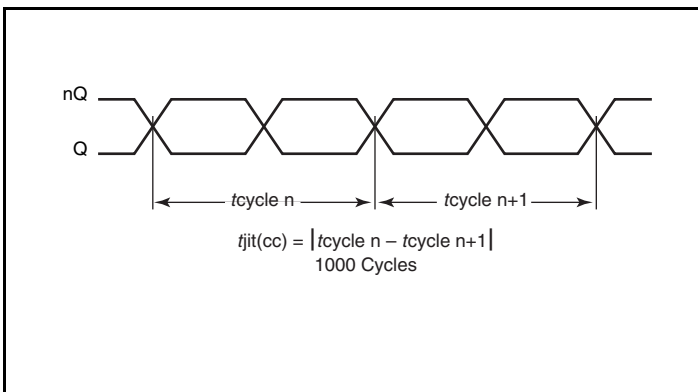
Differential Input Level



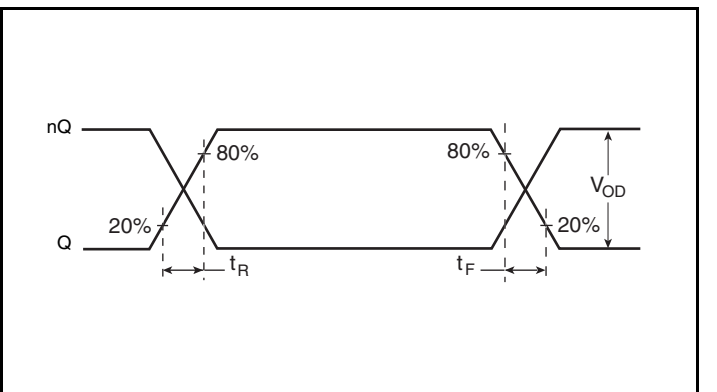
Phase Jitter and Static Phase Offset



Output Skew

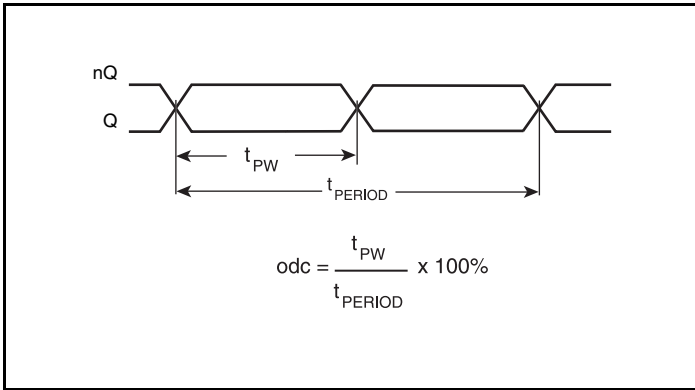


Cycle-to-Cycle Jitter

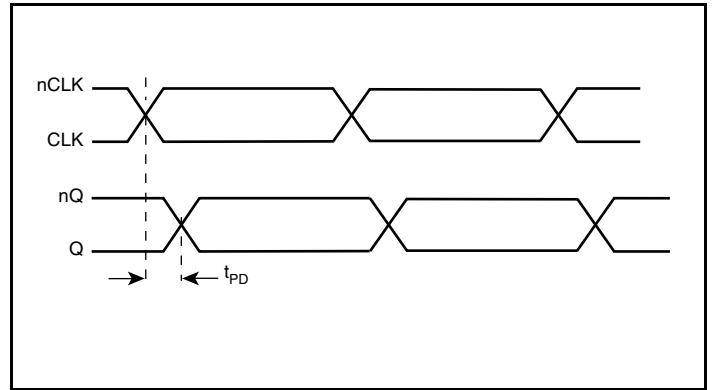


Output Rise/Fall Time

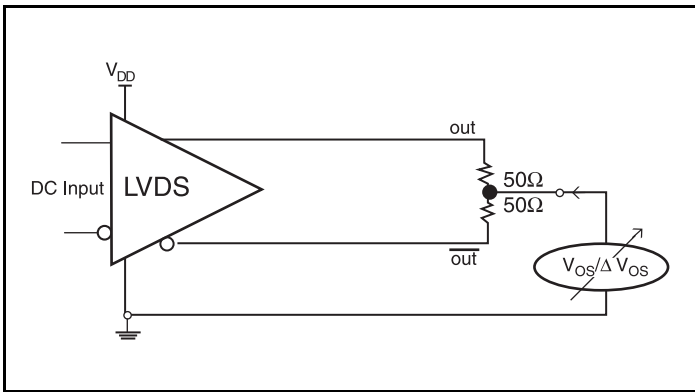
Parameter Measurement Information, continued



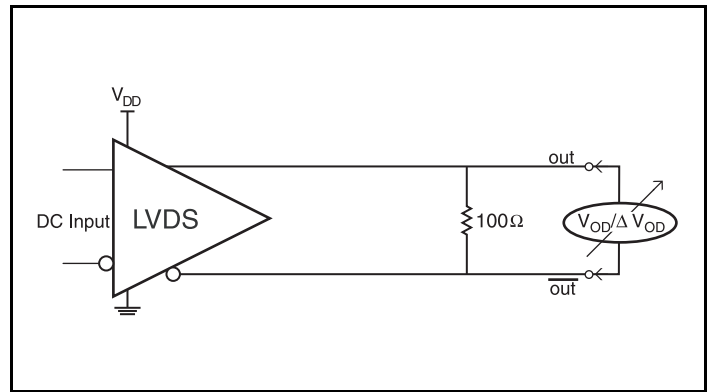
Output Duty Cycle



Propagation Delay



Offset Voltage Setup



Differential Output Voltage Setup

Application Information

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The 8745B-21 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{DD} , V_{DDA} and V_{DDO} should be individually connected to the power supply plane through vias, and $0.01\mu\text{F}$ bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{DD} pin and also shows that V_{DDA} requires that an additional 10Ω resistor along with a $10\mu\text{F}$ bypass capacitor be connected to the V_{DDA} pin.

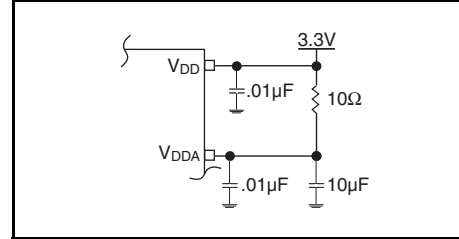


Figure 1. Power Supply Filtering

Wiring the Differential Input to Accept Single Ended Levels

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{DD}/2$ is generated by the bias resistors $R1$, $R2$ and $C1$. This bias circuit should be located as close as possible to the input pin. The ratio of $R1$ and $R2$ might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{DD} = 3.3\text{V}$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.

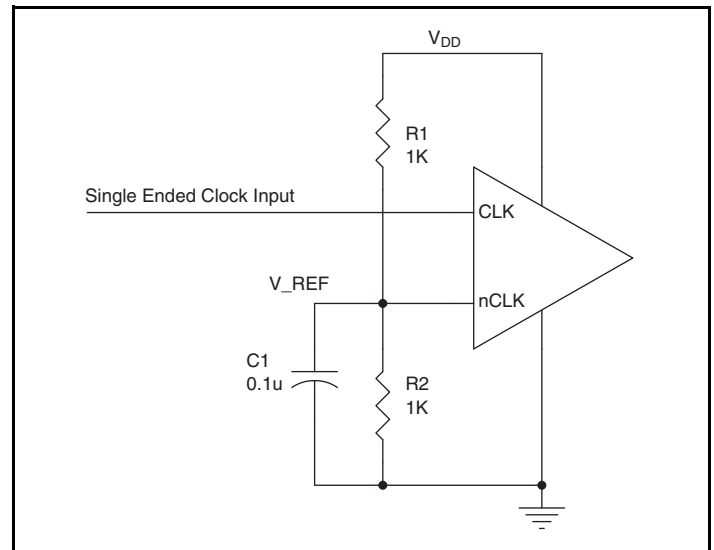
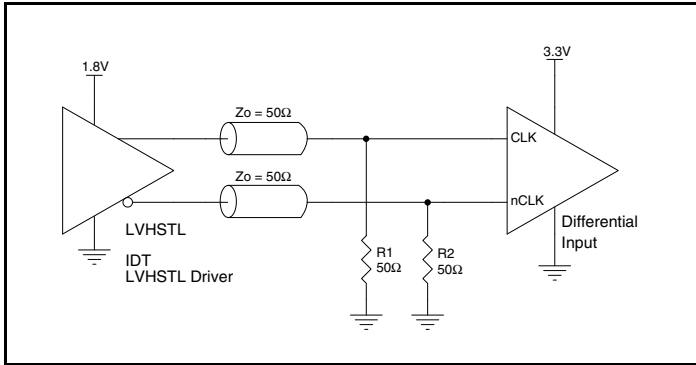


Figure 2. Single-Ended Signal Driving Differential Input

Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the V_{PP} and V_{CMR} input requirements. Figures 3A to 3F show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the

vendor of the driver component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.



3A. CLK/nCLK Input Driven by an IDT Open Emitter LVHSTL Driver

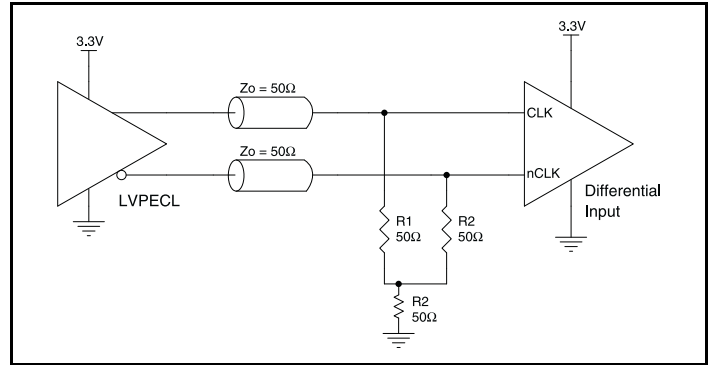


Figure 3B. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

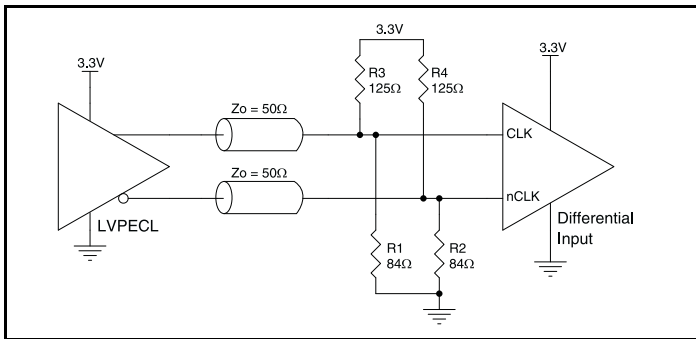


Figure 3C. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

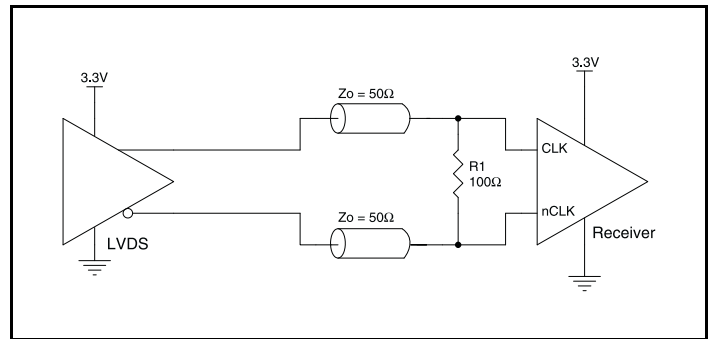


Figure 3D. CLK/nCLK Input Driven by a 3.3V LVDS Driver

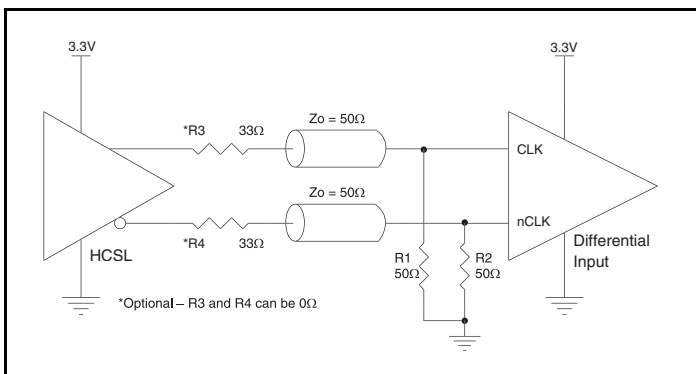


Figure 3E. CLK/nCLK Input Driven by a 3.3V HCSL Driver

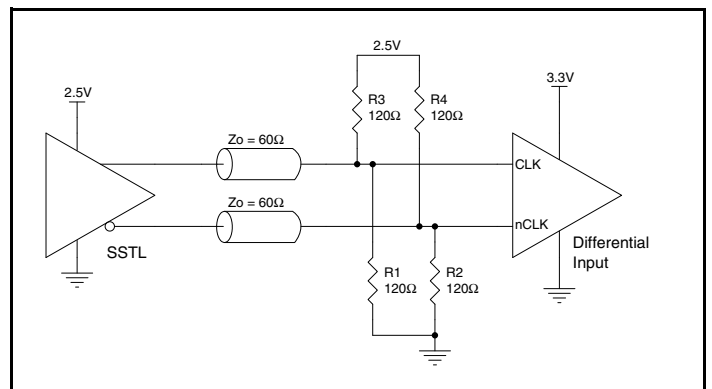


Figure 3F. CLK/nCLK Input Driven by a 2.5V SSTL Driver

Recommendations for Unused Input and Output Pins

Inputs:

LVC MOS Control Pins:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

CLK/nCLK Input

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from CLK to ground.

Outputs:

LVDS Output

All unused LVDS output pairs can be either left floating or terminated with 100Ω across. If they are left floating, we recommend that there is no trace attached.

3.3V LVDS Driver Termination

A general LVDS interface is shown in *Figure 4*. In a 100Ω differential transmission line environment, LVDS drivers require a matched load termination of 100Ω across near the receiver input. For a multiple

LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the unused outputs.

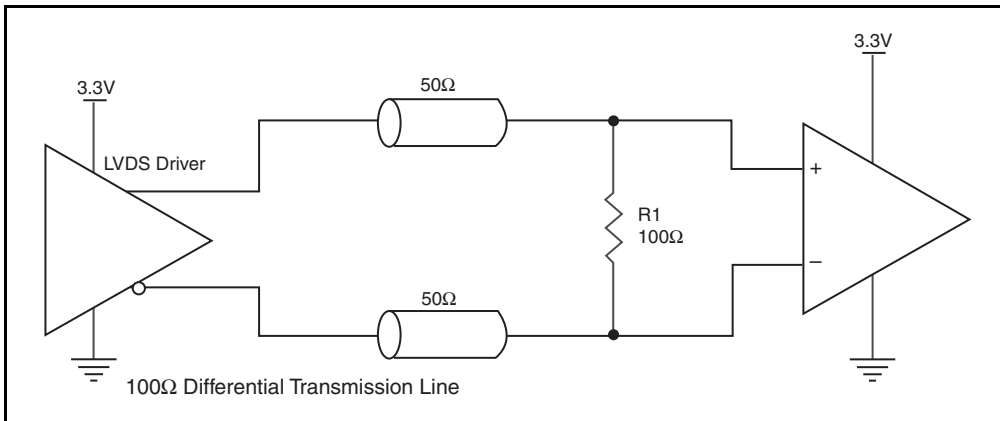


Figure 4. Typical LVDS Driver Termination

Schematic Example

The schematic of the 8745B-21 layout example is shown in *Figure 5A*. The 8745B-21 recommended PCB board layout for this example is shown in *Figure 5B*. This layout example is used as a general

guideline. The layout in the actual system will depend on the selected component types, the density of the components, the density of the traces, and the stack up of the P.C. board.

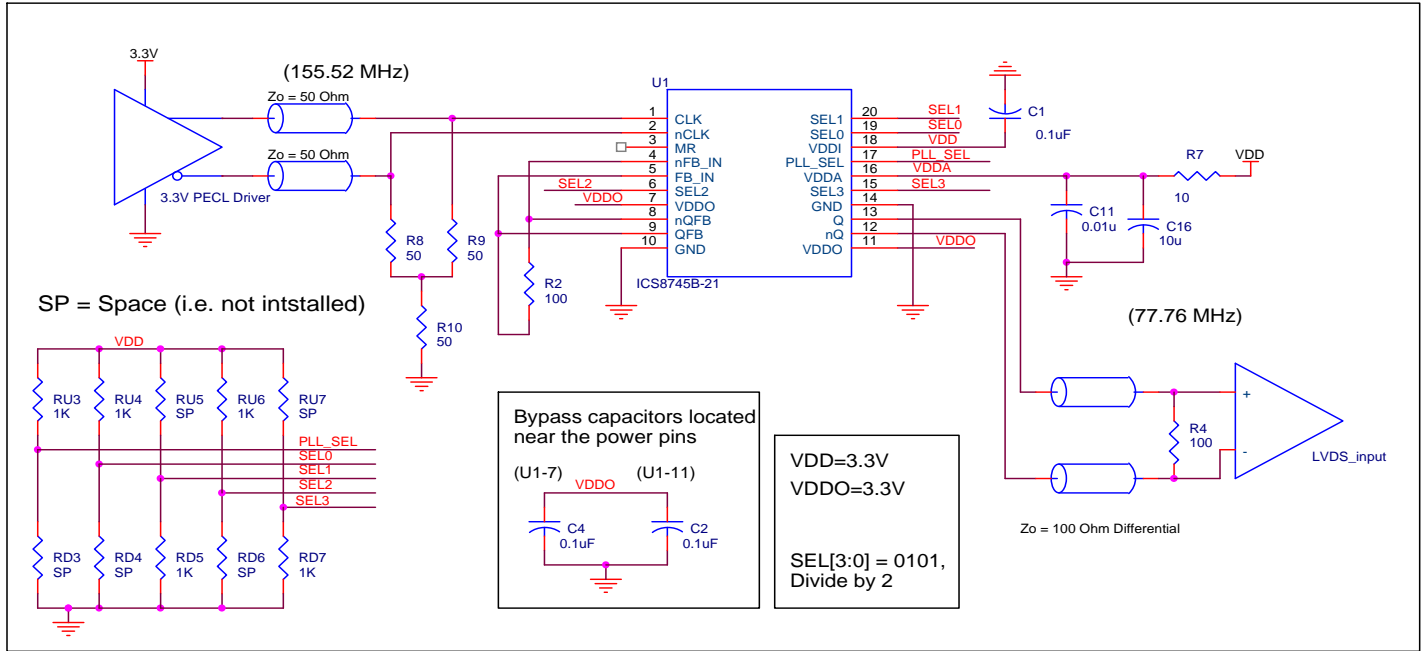


Figure 5A. 8745B-21 LVDS Zero Delay Buffer Schematic Example

The following component footprints are used in this layout example.

All the resistors and capacitors are size 0603.

Power and Grounding

Place the decoupling capacitors as close as possible to the power pins. If space allows, placement of the decoupling capacitor on the component side is preferred. This can reduce unwanted inductance between the decoupling capacitor and the power pin caused by the via.

Maximize the power and ground pad sizes and number of vias capacitors. This can reduce the inductance between the power and ground planes and the component power and ground pins.

The RC filter consisting of R7, C11, and C16 should be placed as close to the V_{DDA} pin as possible.

Clock Traces and Termination

Poor signal integrity can degrade the system performance or cause system failure. In synchronous high-speed digital systems, the clock signal is less tolerant to poor signal integrity than other signals. Any ringing on the rising or falling edge or excessive ring back can cause system failure. The shape of the trace and the trace delay might be

restricted by the available space on the board and the component location. While routing the traces, the clock signal traces should be routed first and should be locked prior to routing other signal traces.

- The differential 50Ω output traces should have the same length.
- Avoid sharp angles on the clock trace. Sharp angle turns cause the characteristic impedance to change on the transmission lines.
- Keep the clock traces on the same layer. Whenever possible, avoid placing vias on the clock traces. Placement of vias on the traces can affect the trace characteristic impedance and hence degrade signal integrity.
- To prevent cross talk, avoid routing other signal traces in parallel with the clock traces. If running parallel traces is unavoidable, allow a separation of at least three trace widths between the differential clock trace and the other signal trace.
- Make sure no other signal traces are routed between the clock trace pair.
- The matching termination resistors should be located as close to the receiver input pins as possible.

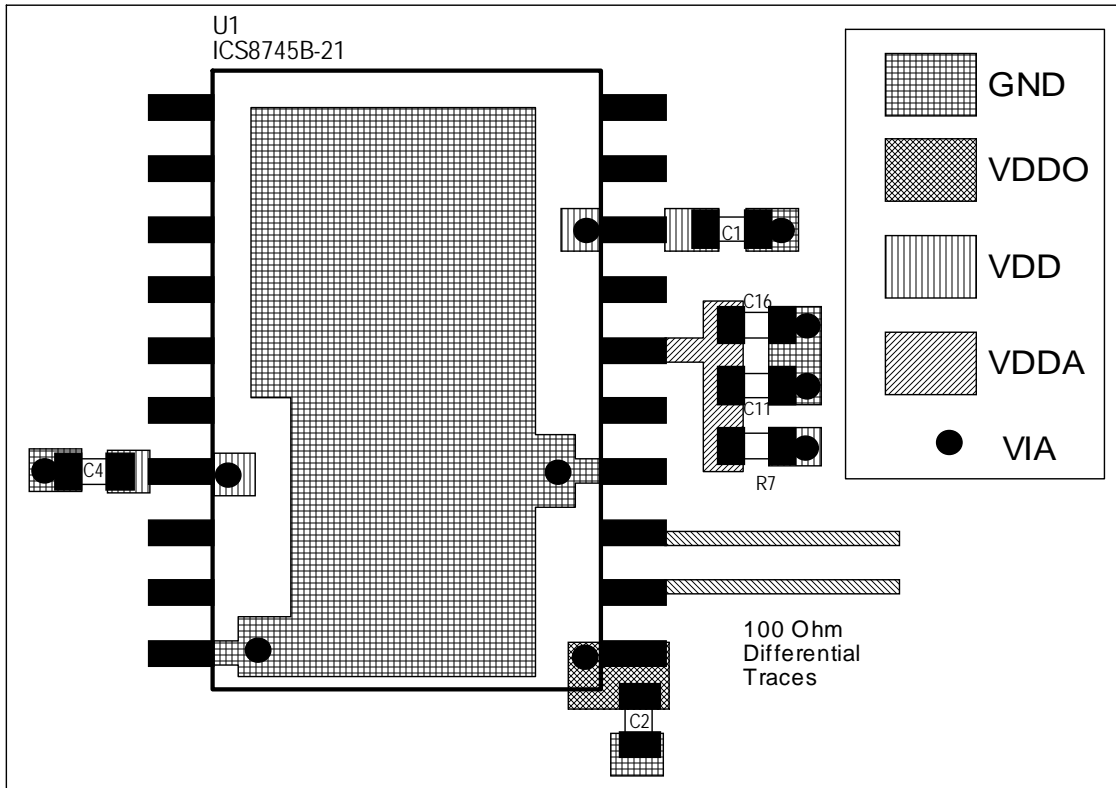


Figure 5B. PCB Board Layout for 8745B-21

Power Considerations

This section provides information on power dissipation and junction temperature for the 8745B-21. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 8745B-21 is the sum of the core power plus the analog power plus the power dissipated in the load(s). The following is the power dissipation for $V_{DD} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{DD_MAX} * (I_{DD_MAX} + I_{DDA_MAX}) = 3.465V * (125mA + 17mA) = 492mW$
- Power (outputs)_{MAX} = $V_{DDO_MAX} * I_{DDO_MAX} = 3.465V * 59mA = 204mW$

Total Power_{MAX} = 492mW + 204mW = 696mW

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature, T_j , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 39.7°C/W per Table 7 below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ\text{C} + 0.696\text{W} * 39.7^\circ\text{C}/\text{W} = 97.6^\circ\text{C}. \text{ This is well below the limit of } 125^\circ\text{C}.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 7. Thermal Resistance θ_{JA} for 20 Lead SOIC, Forced Convection

θ_{JA} vs. Air Flow			
Linear Feet per Minute	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	83.2°C/W	65.7°C/W	57.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	46.2°C/W	39.7°C/W	36.8°C/W
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			

Reliability Information

Table 8. θ_{JA} vs. Air Flow Table for a 20 Lead SOIC

θ_{JA} vs. Air Flow			
Linear Feet per Minute	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	83.2°C/W	65.7°C/W	57.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	46.2°C/W	39.7°C/W	36.8°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

Transistor Count

The transistor count for 8745B-21 is: 2772

Package Outline and Package Dimensions

Package Outline - M Suffix for 20 Lead SOIC

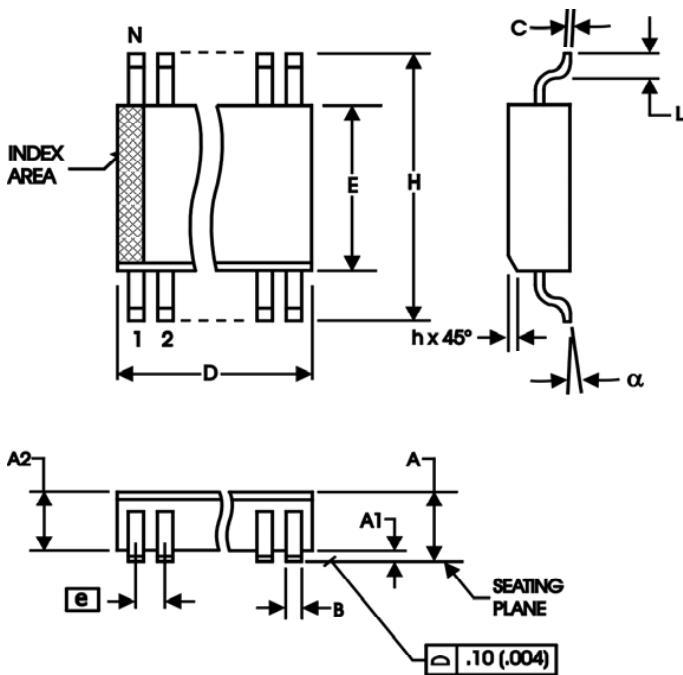


Table 9. Package Dimensions for 20 Lead SOIC

300 Millimeters All Dimensions in Millimeters		
Symbol	Minimum	Maximum
N	20	
A		2.65
A1	0.10	
A2	2.05	2.55
B	0.33	0.51
C	0.18	0.32
D	12.60	13.00
E	7.40	7.60
e	1.27 Basic	
H	10.00	10.65
h	0.25	0.75
L	0.40	1.27
α	0°	7°

Reference Document: JEDEC Publication 95, MS-013, MS-119

Ordering Information

Table 10. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8745BM-21LF	ICS8745BM-21LF	"Lead-Free" 20 Lead SOIC	Tube	0°C to 70°C
8745BM-21LFT	ICS8745BM-21LF	"Lead-Free" 20 Lead SOIC	1000 Tape & Reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

Revision History Sheet

Rev	Table	Page	Description of Change	Date
B	T4D	5	LVDS DC Characteristics Table - modified VOS 0.90V min. to 1.05V min, 1.15V typical to 1.2V typical, and 1.4V max. to 1.35V max.	3/17/04
B	T9	1 14	Added Lead-Free bullet. Ordering Information Table - added Lead-Free part and note.	12/2/04
C	T6	7 12 15	AC Characteristics Table - changed t_{PD} max limit from 3.7ns to 4.0ns. Added Recommendations for Unused Input & Output Pins. Added Power Considerations section. Updated format throughout the datasheet.	4/17/07
D	T4C T6 T10	1 6 7 10 11 17	Pin Assignment - corrected lineup of pin names. Differential DC Characteristics Table - updated NOTES. AC Characteristics Table - added thermal note. Power Supply Filtering Technique - updated paragraph. Updated <i>Differential Clock Input Interface</i> . Ordering Information Table - added "LF" marking. Deleted "ICS" prefix in Part/Order number column. Updated Header/Footer of datasheet.	1/25/10
D	T10	17	Ordering Information - Removed leaded Devices - PDN CQ-13-02 Updated Datasheet format	2/17/15

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
 2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
 3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
 4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
 5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
 - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
 - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
 6. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
 7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
 8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
 9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
 10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
 11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
 12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.